

[BUMPING PROCESS]

Abstract

A bumping process is disclosed. The bumping process comprises the steps of: providing a wafer having a plurality of bonding pads and a passivation layer, wherein the passivation layer exposes the bonding pads; forming an UBM layer over the wafer to cover the bonding pads; forming two or more photoresist layers over the wafer, wherein the photoresist layers have different exposure and development characteristics; forming at least one or more stair-shaped openings in the photoresist layers by a single exposure corresponding to the bonding pads; filling solder into the stair-shaped openings to form a plurality of solder bumps; removing the entire photoresist layer. The bumping process can provide bumps with higher heights, so that the connection between chips and carriers becomes more reliable.